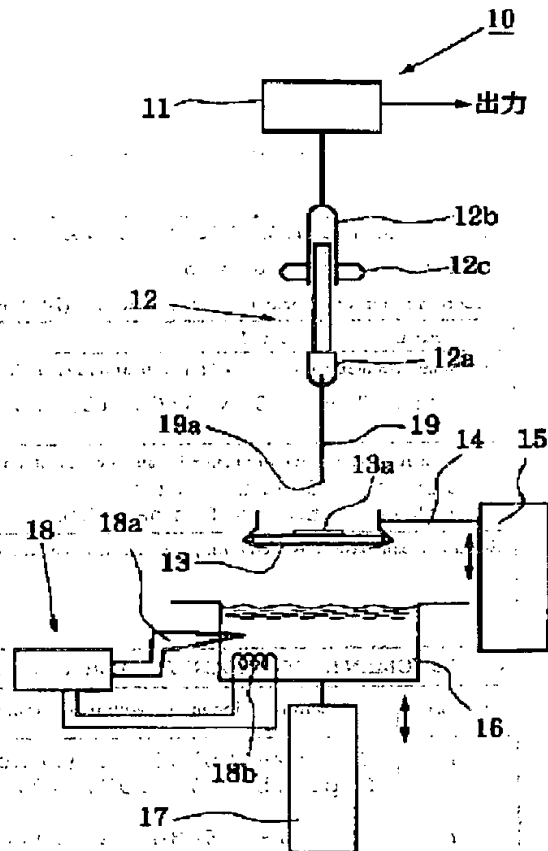


Patent Abstracts of Japan

TITLE : METHOD AND APPARATUS FOR TESTING SOLDERABILITY OF ELECTRONIC COMPONENT



CONSTITUTION: The apparatus 10 for testing solderability of electronic components is provided with an external force detecting means 11 for supporting a component holding means 12 via a slide shaft mechanism 12b, a locking mechanism 12c capable of locking the slide shaft mechanism, a supporting member 14 for supporting a component bonding member 13 provided below the component holding means in a movable fashion in the vertical direction, and a solder bath 16 for accommodating a molten solder of constant temperatures which is supported below the supporting member to be movable up and down.

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